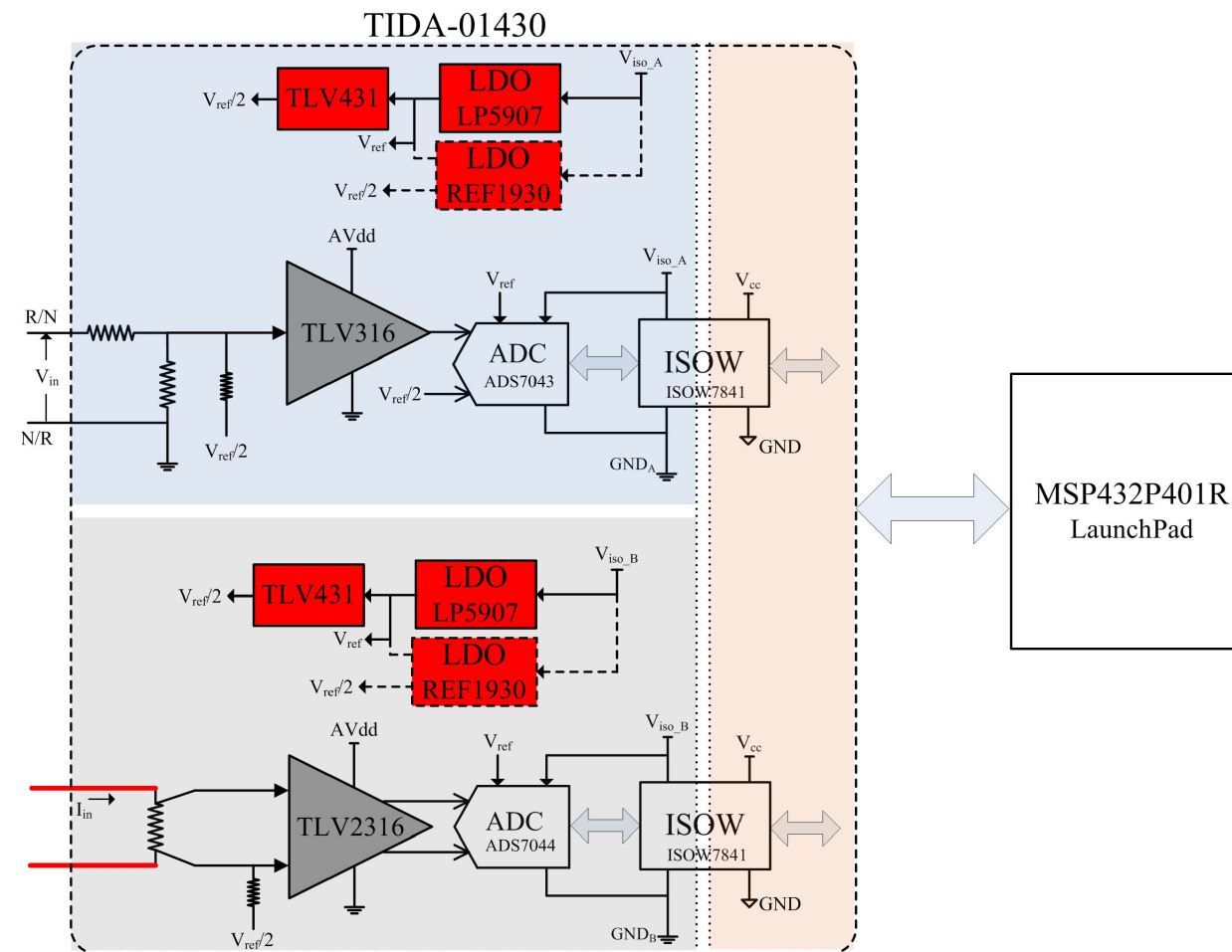


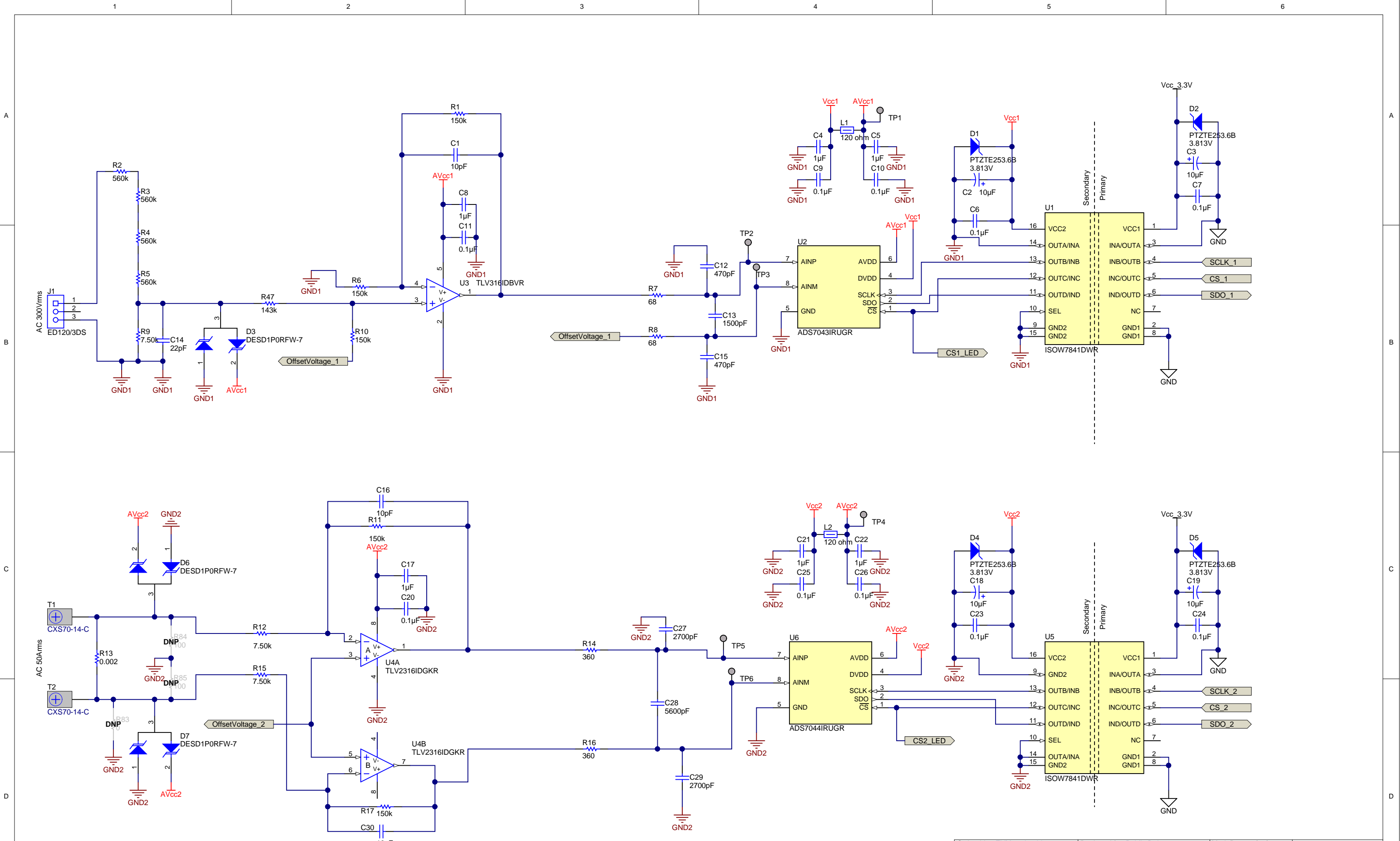
Revision History

Rev	ECN #	Approved Date	Approved by	Notes
N/A	N/A	N/A	N/A	N/A



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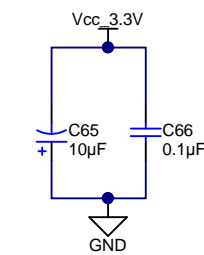
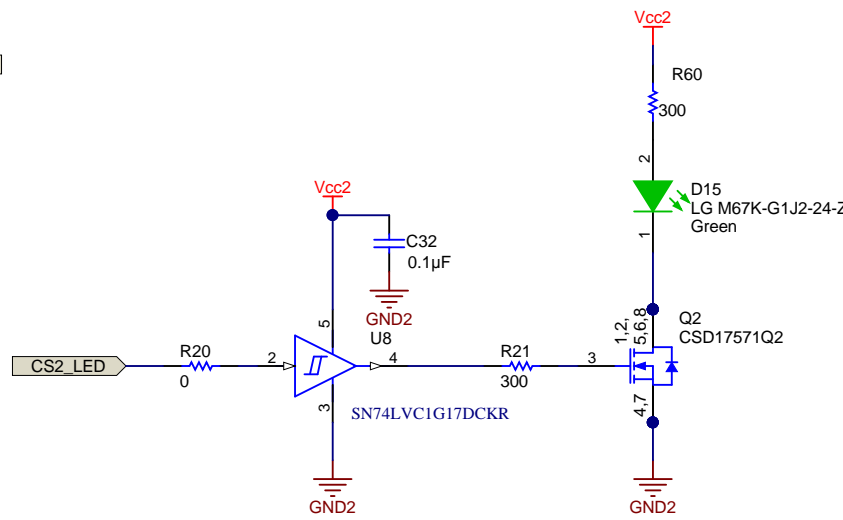
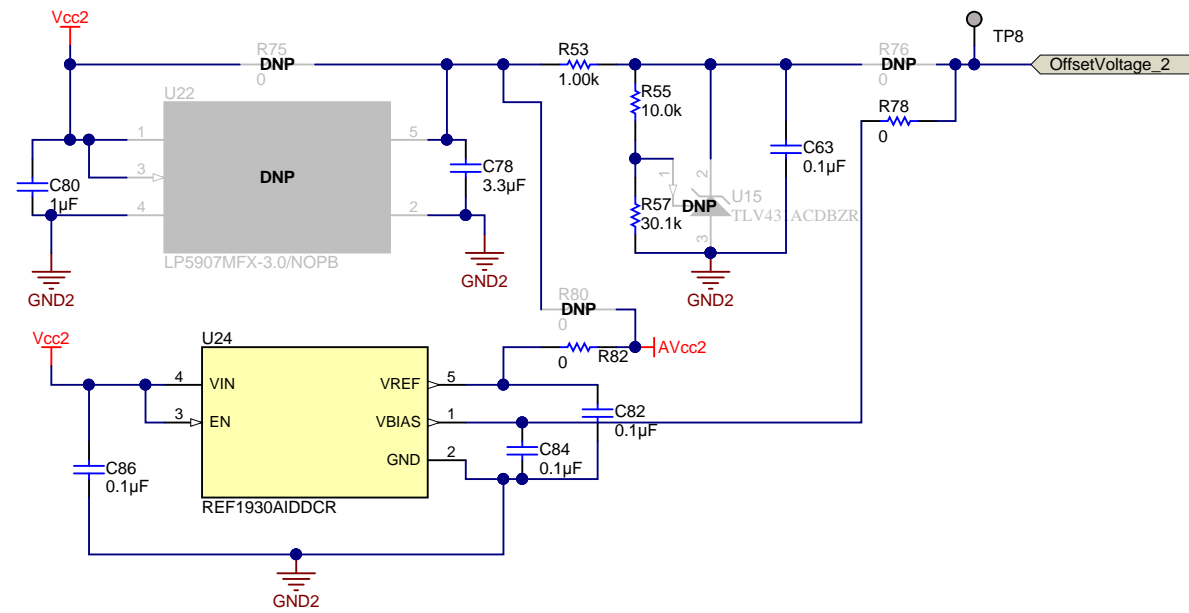
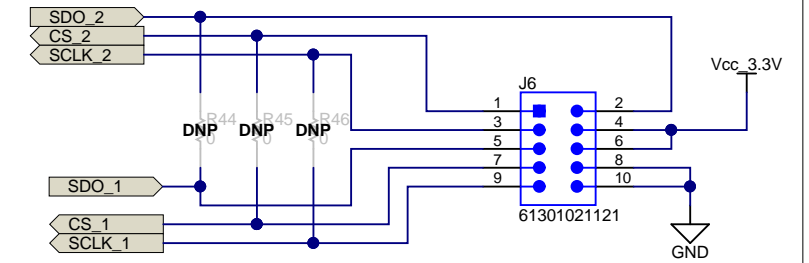
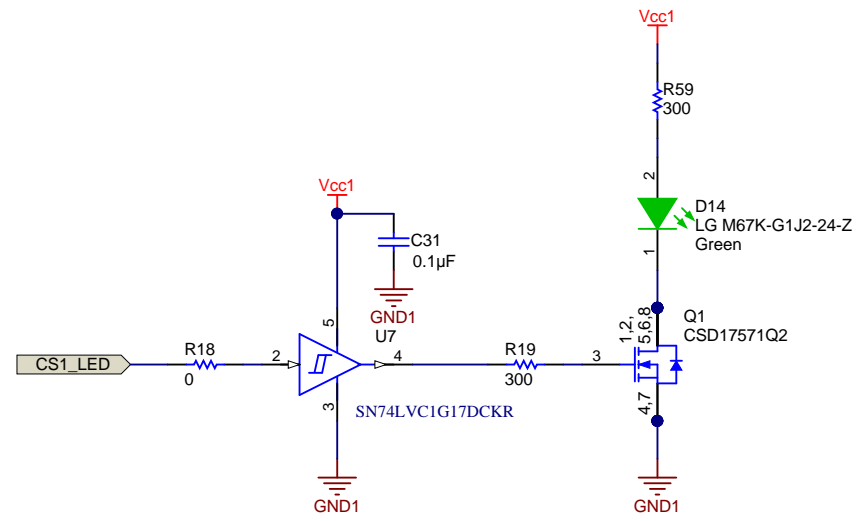
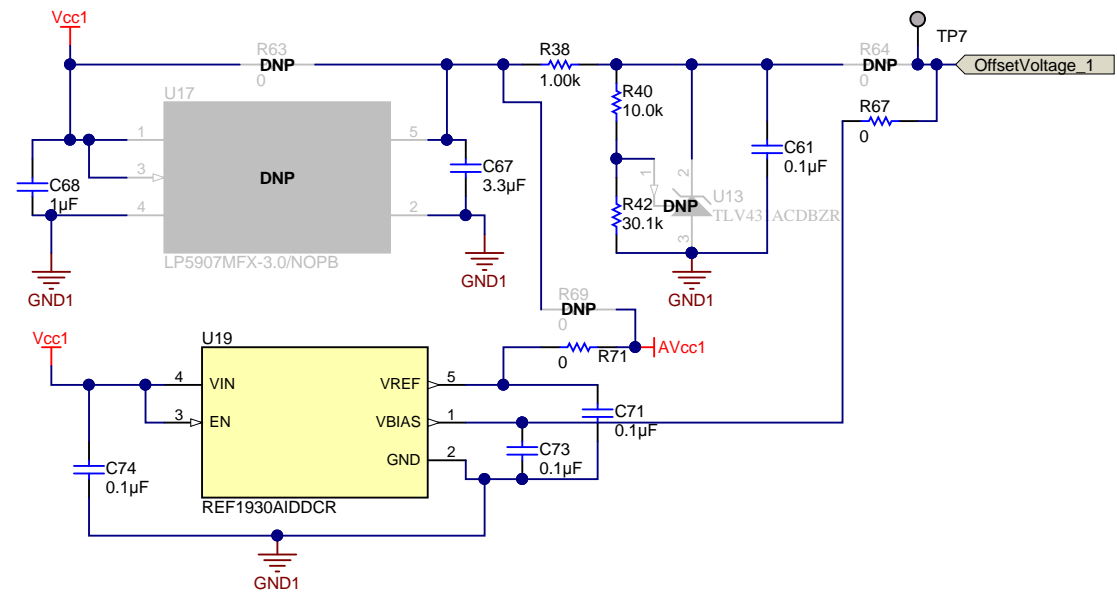
Orderable: EVM_orderable	Designed for: Public Release	Mod. Date: 4/26/2017	 http://www.ti.com © Texas Instruments 2017
TID #: TIDA-01430	Project Title: Small Form Factor, Ultra-low Power, Channel-Chan		
Number: TIDA-01430	Rev: E1	Sheet Title:	
SVN Rev: Version control disabled	Assembly Variant: 003	Sheet: 1 of 3	
Drawn By:	File: TIDA-01430_CoverSheet_SchDoc	Size: B	
Engineer: Prasanna Rajagopal	Contact: http://www.ti.com/support		



Orderable: EVM_orderable	Designed for: Public Release	Mod. Date: 4/27/2017
TID #: TIDA-01430	Project Title: Small Form Factor, Ultra-low Power, Channel-Chan	
Number: TIDA-01430	Rev: E1	Sheet: 2 of 3
SVN Rev: Version control disabled	Assembly Variant: 003	Size: B
Drawn By: Prasanna Rajagopal	File: TIDA-01430_sheet1.SchDoc	
Engineer: Prasanna Rajagopal	Contact: http://www.ti.com/support	

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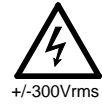




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Orderable: EVM_orderable	Designed for: Public Release	Mod. Date: 4/27/2017	
TID #: TIDA-01430	Project Title: Small Form Factor, Ultra-low Power, Channel-Chan	Sheet: 2 of 3	
Number: TIDA-01430	Rev: E1	File: TIDA-01430_Connectors.SchDoc	Size: B
SVN Rev: Version control disabled	Assembly Variant: 003	Contact: http://www.ti.com/support	© Texas Instruments 2017
Drawn By:	Engineer: Prasanna Rajagopal		

H1 SJ-5303 (CLEAR) H2 SJ-5303 (CLEAR) H3 SJ-5303 (CLEAR) H4 SJ-5303 (CLEAR)



PCB Number: TIDA-01430
PCB Rev: E1

PCB LOGO
Texas Instruments

PCB LOGO
Pb-Free Symbol

PCB LOGO
FCC disclaimer

Variant/Label Table	
Variant	Label Text
001	ChangeMe!
002	ChangeMe!

LBL1
PCB Label
Size: 0.65" x 0.20 "

ZZ1
Label Assembly Note
This Assembly Note is for PCB labels only

ZZ2
Assembly Note
These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3
Assembly Note
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4
Assembly Note
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

Orderable: EVM_orderable	Designed for: Public Release	Mod. Date: 4/26/2017	<p>TEXAS INSTRUMENTS http://www.ti.com © Texas Instruments 2017</p>
TID #: TIDA-01430	Project Title: Small Form Factor, Ultra-low Power, Channel-Chan		
Number: TIDA-01430	Rev: E1	Sheet Title:	
SVN Rev: Version control disabled	Assembly Variant: 003	Sheet: 3 of 3	
Drawn By:	File: TIDA-01430_EVM_Hardware.SchDoc	Size: B	
Engineer: Prasanna Rajagopal	Contact: http://www.ti.com/support		

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